

Chapter 8 Bipolar Junction Transistors

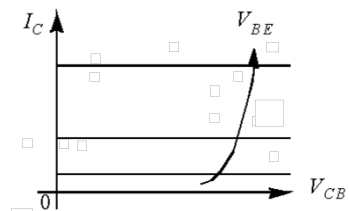
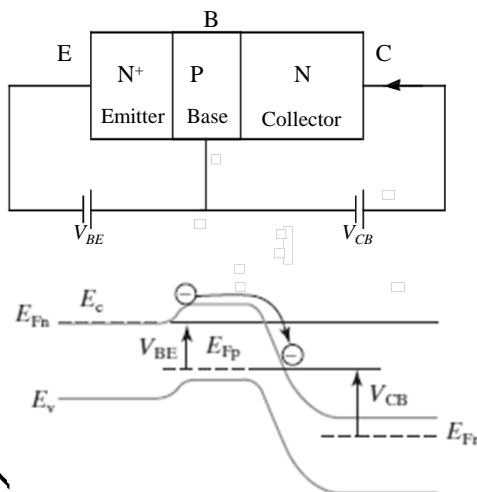
- Since 1970, the high density and low-power advantage of the MOS technology steadily eroded the BJT's early dominance.
- BJTs are still preferred in some high-frequency and analog applications because of their high speed and high power output.

Question: What is the meaning of “bipolar” ?

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8.1 Introduction to the BJT

NPN BJT:



I_C is an exponential function of forward V_{BE} and independent of reverse V_{CB} .

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Common-Emitter Configuration

Question: Why is I_B often preferred as a parameter over V_{BE} ?

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8.2 Collector Current

$$\frac{d^2 n'}{dx^2} = \frac{n'}{L_B^2}$$

$$L_B \equiv \sqrt{\tau_B D_B}$$

τ_B : base recombination lifetime
 D_B : base minority carrier (electron) diffusion constant

Boundary conditions :

$$n'(0) = n_{B0} (e^{qV_{BE}/kT} - 1)$$

$$n'(W_B) = n_{B0} (e^{qV_{BC}/kT} - 1) \approx -n_{B0} \approx 0$$

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8.2 Collector Current

$$n'(x) = n_{B0} (e^{qV_{BE}/kT} - 1) \frac{\sinh\left(\frac{W_B - x}{L_B}\right)}{\sinh(W_B/L_B)}$$

$$n'(x) = \frac{n_{iB}^2}{N_B} (e^{qV_{BE}/kT} - 1)$$

$$n'(x) = n'(0)(1 - x/W_B)$$

$$= \frac{n_{iB}^2}{N_B} (e^{qV_{BE}/kT} - 1)(1 - x/W_B)$$

$$I_C = \left| A_E q D_B \frac{dn}{dx} \right|$$

$$= A_E q \frac{D_B}{W_B} \frac{n_{iB}^2}{N_B} (e^{qV_{BE}/kT} - 1)$$

$$I_C = I_S (e^{qV_{BE}/kT} - 1)$$

It can be shown

$$I_C = A_E \frac{qn_i^2}{G_B} (e^{qV_{BE}/kT} - 1)$$

$$G_B \equiv \int_0^{W_B} \frac{n_i^2}{n_{iB}^2} \frac{p}{D_B} dx$$

G_B ($s \cdot cm^4$) is the **base Gummel number**

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8.3 Base Current

Some holes are injected from the P-type base into the N^+ emitter. The holes are provided by the base current, I_B .

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8.3 Base Current

$I_B = A_E \frac{qn_i^2}{G_E} (e^{qV_{BE}/kT} - 1)$
□ For a uniform emitter,

$G_E \equiv \int_0^{W_E} \frac{n_i^2}{n_{iE}^2} \frac{n}{D_E} dx$
□ $I_B = A_E q \frac{D_E n_{iE}^2}{W_E N_E} (e^{qV_{BE}/kT} - 1)$

Is a large I_B desirable? Why?

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8.4 Current Gain

Common-emitter current gain, β_F : $\beta_F \equiv \frac{I_C}{I_B}$

Common-base current gain:

$I_C = \alpha_F I_E$

$\alpha_F \equiv \frac{I_C}{I_E} = \frac{I_C}{I_B + I_C} = \frac{I_C / I_B}{1 + I_C / I_B} = \frac{\beta_F}{1 + \beta_F}$

It can be shown that $\beta_F = \frac{\alpha_F}{1 - \alpha_F}$

$$\beta_F = \frac{G_E}{G_B} = \frac{D_B W_E N_E n_{iB}^2}{D_E W_B N_B n_{iE}^2}$$

How can β_F be maximized?

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EXAMPLE: Current Gain

A BJT has $I_C = 1 \text{ mA}$ and $I_B = 10 \text{ } \mu\text{A}$. What are I_E , β_F and α_F ?

Solution:

$$I_E = I_C + I_B = 1 \text{ mA} + 10 \text{ } \mu\text{A} = 1.01 \text{ mA}$$

$$\beta_F = I_C / I_B = 1 \text{ mA} / 10 \text{ } \mu\text{A} = 100$$

$$\alpha_F = I_C / I_E = 1 \text{ mA} / 1.01 \text{ mA} = 0.9901$$

We can confirm

$$\alpha_F = \frac{\beta_F}{1 + \beta_F} \quad \text{and} \quad \beta_F = \frac{\alpha_F}{1 - \alpha_F}$$

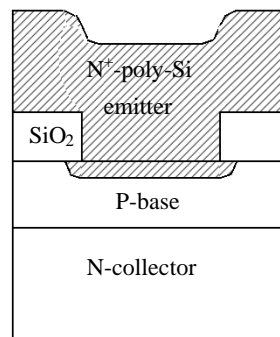
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8.4.3 Poly-Silicon Emitter

A high-performance BJT typically has a layer of As-doped N^+ poly-silicon film in the emitter.

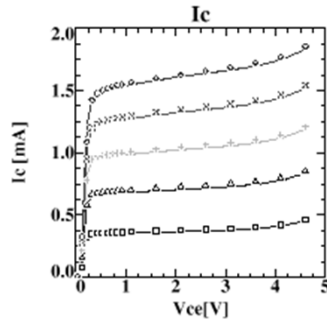
β_F is larger due to the large W_E , mostly made of the N^+ poly-silicon. (A deep diffused emitter junction tends to cause emitter-collector shorts.)



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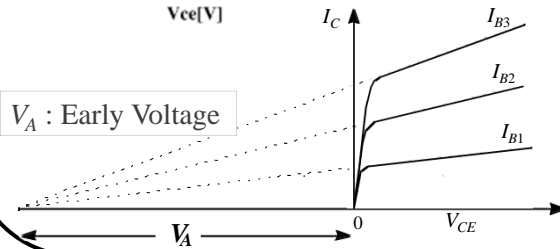
8.5 Base-Width Modulation by Collector Voltage



Output resistance :

$$r_o \equiv \left(\frac{\partial I_C}{\partial V_{CE}} \right)^{-1} = \frac{V_A}{I_C}$$

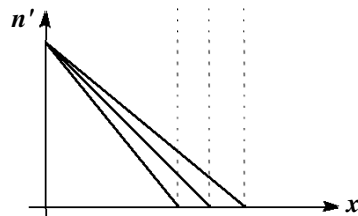
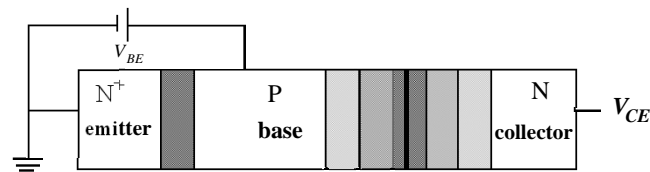
V_A : Early Voltage



Large V_A (large r_o) is desirable for a large voltage gain

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8.5 Base-Width Modulation by Collector Voltage



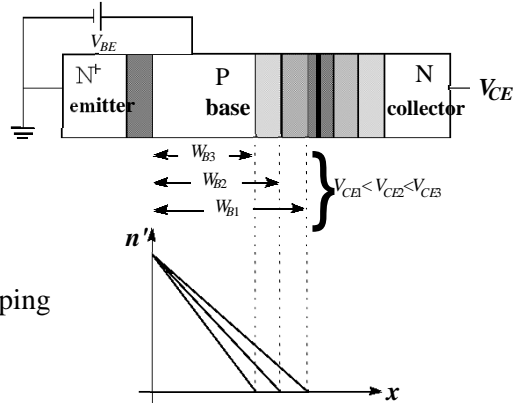
How can we reduce the base-width modulation effect?

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8.5 Base-Width Modulation by Collector Voltage

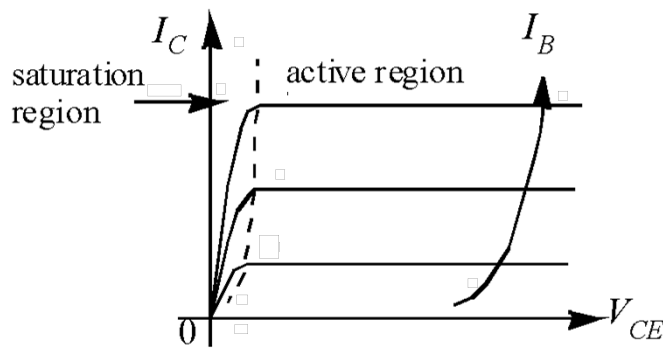
The base-width modulation effect is reduced if we

- (A) Increase the base width,
- (B) Increase the base doping concentration, N_B , or
- (C) Decrease the collector doping concentration, N_C .



Which of the above is the most acceptable action?

8.6 Ebers-Moll Model



The Ebers-Moll model describes both the active and the saturation regions of BJT operation.

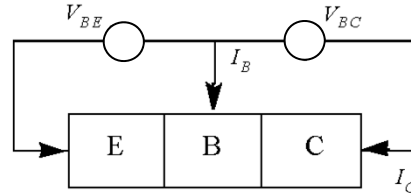
8.6 Ebers-Moll Model

I_C is driven by two forces, V_{BE} and V_{BC} .

When only V_{BE} is present :

$$I_C = I_S (e^{qV_{BE}/kT} - 1)$$

$$I_B = \frac{I_S}{\beta_F} (e^{qV_{BE}/kT} - 1)$$



Now reverse the roles of emitter and collector.

When only V_{BC} is present :

$$I_E = I_S (e^{qV_{BC}/kT} - 1)$$

β_R : reverse current gain

$$I_B = \frac{I_S}{\beta_R} (e^{qV_{BC}/kT} - 1)$$

β_F : forward current gain

$$I_C = -I_E - I_B = -I_S \left(1 + \frac{1}{\beta_R}\right) (e^{qV_{BC}/kT} - 1)$$

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8.6 Ebers-Moll Model

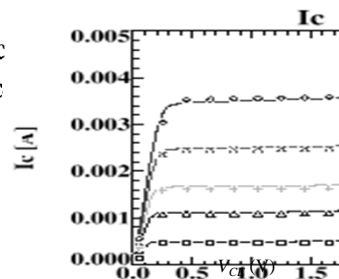
In general, both V_{BE} and V_{BC} are present :

$$I_C = I_S (e^{qV_{BE}/kT} - 1) - I_S \left(1 + \frac{1}{\beta_R}\right) (e^{qV_{BC}/kT} - 1)$$

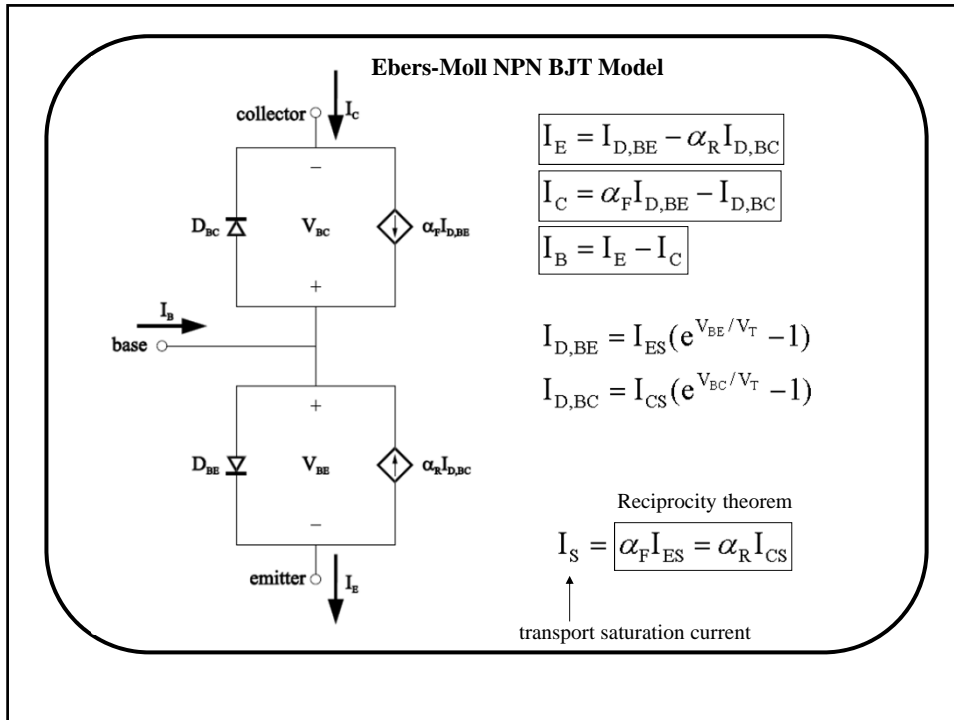
$$I_B = \frac{I_S}{\beta_F} (e^{qV_{BE}/kT} - 1) + \frac{I_S}{\beta_R} (e^{qV_{BC}/kT} - 1)$$

In saturation, the BC junction becomes forward-biased, too.

V_{BC} causes a lot of holes to be injected into the collector. This uses up much of I_B . As a result, I_C drops.

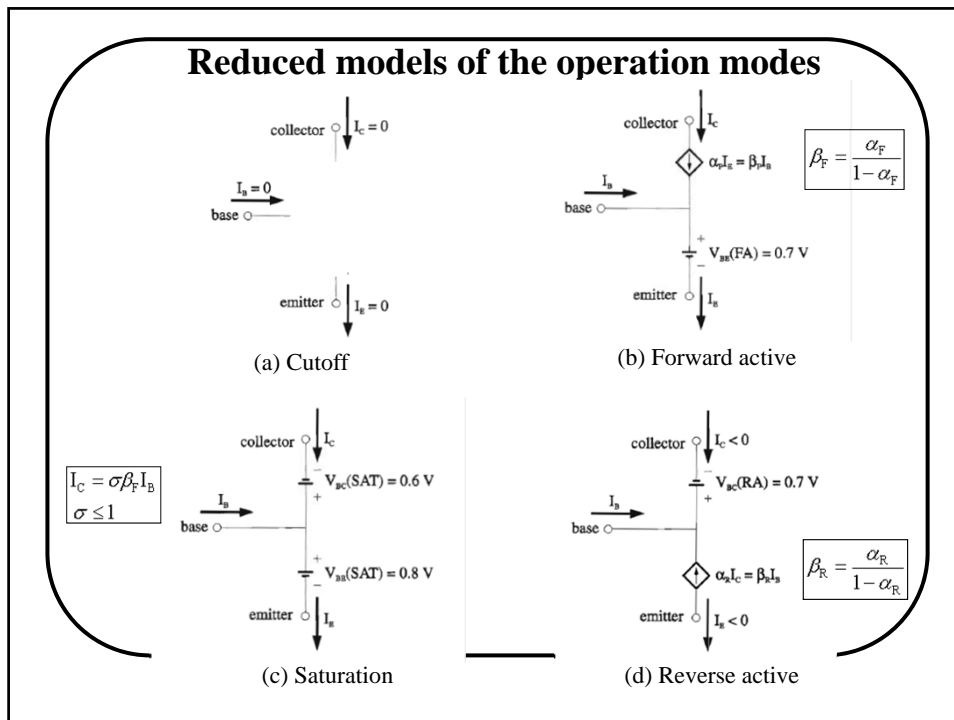


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BJT Modes of Operation

| BE junction | BC junction | Mode |
|-------------|-------------|---------------------|
| Reverse | Reverse | Cutoff (OFF) |
| Forward | Reverse | Forward active (FA) |
| Forward | Forward | Saturation (SAT) |
| Reverse | Forward | Reverse active (RA) |



8.7 Transit Time and Charge Storage

When the BE junction is forward-biased, excess holes are stored in the emitter, the base, and even in the depletion layers.

Q_F is all the stored excess hole charge

$$\tau_F \equiv \frac{Q_F}{I_C}$$

τ_F is difficult to be predicted accurately but can be measured.

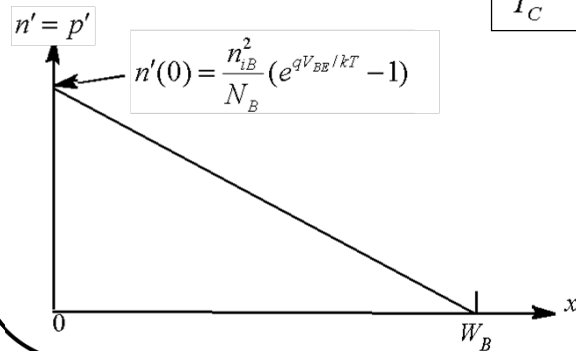
τ_F determines the high-frequency limit of BJT operation.

8.7.1 Base Charge Storage and Base Transit Time

Let's analyze the excess hole charge and transit time in the base only.

$$Q_{FB} = qA_E n'(0)W_B / 2$$

$$\frac{Q_{FB}}{I_C} \equiv \tau_{FB} = \frac{W_B^2}{2D_B}$$



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EXAMPLE: Base Transit Time

What is τ_{FB} if $W_B = 70 \text{ nm}$ and $D_B = 10 \text{ cm}^2/\text{s}$?

Answer:

$$\tau_{FB} = \frac{W_B^2}{2D_B} = \frac{(7 \times 10^{-6} \text{ cm})^2}{2 \times 10 \text{ cm}^2/\text{s}} = 2.5 \times 10^{-12} \text{ s} = 2.5 \text{ ps}$$

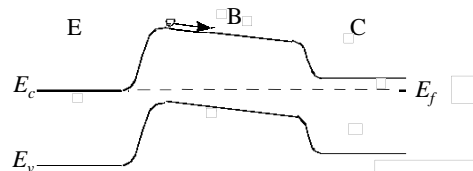
2.5 ps is a very short time. Since light speed is $3 \times 10^8 \text{ m/s}$, light travels only 1.5 mm in 5 ps.

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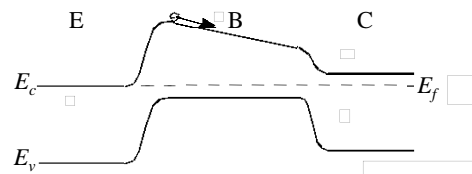
8.7.2 Drift Transistor–Built-in Base Field

The base transit time can be reduced by building into the base a drift field that aids the flow of electrons. Two methods:

- Fixed E_{gB} , N_B decreases from emitter end to collector end.



- Fixed N_B , E_{gB} decreases from emitter end to collector end.



$$\mathbf{E} = \frac{1}{q} \frac{dE_c}{dx}$$

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8.12 Chapter Summary

- The base-emitter junction is usually forward-biased while the base-collector is reverse-biased. V_{BE} determines the collector current, I_C .

$$I_C = A_E \frac{qn_i^2}{G_B} (e^{qV_{BE}/kT} - 1)$$

$$G_B \equiv \int_0^{W_B} \frac{n_i^2}{n_{iB}^2} \frac{p}{D_B} dx$$

- G_B is the base Gummel number, which represents all the subtleties of BJT design that affect I_C .

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8.12 Chapter Summary

- The base (input) current, I_B , is related to I_C by the common-emitter current gain, β_F . This can be related to the common-base current gain, α_F .

$$\beta_F = \frac{I_C}{I_B} \approx \frac{G_E}{G_B} \quad \alpha_F = \frac{I_C}{I_E} = \frac{\beta_F}{1 + \beta_F}$$

- The Gummel plot shows that β_F falls off in the high I_C region due to high-level injection in the base. It also falls off in the low I_C region due to excess base current.
- Base-width modulation by V_{CB} results in a significant slope of the I_C vs. V_{CE} curve in the active region (known as the Early effect).

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8.12 Chapter Summary

- Due to the forward bias V_{BE} , a BJT stores a certain amount of excess carrier charge Q_F which is proportional to I_C .

$$Q_F \equiv I_C \tau_F$$

τ_F is the forward transit time.

If no excess carriers are stored outside the base, then

$$\tau_F = \tau_{FB} = \frac{W_B^2}{2D_B}, \text{ the base transit time.}$$

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